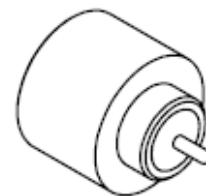
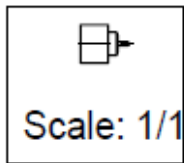
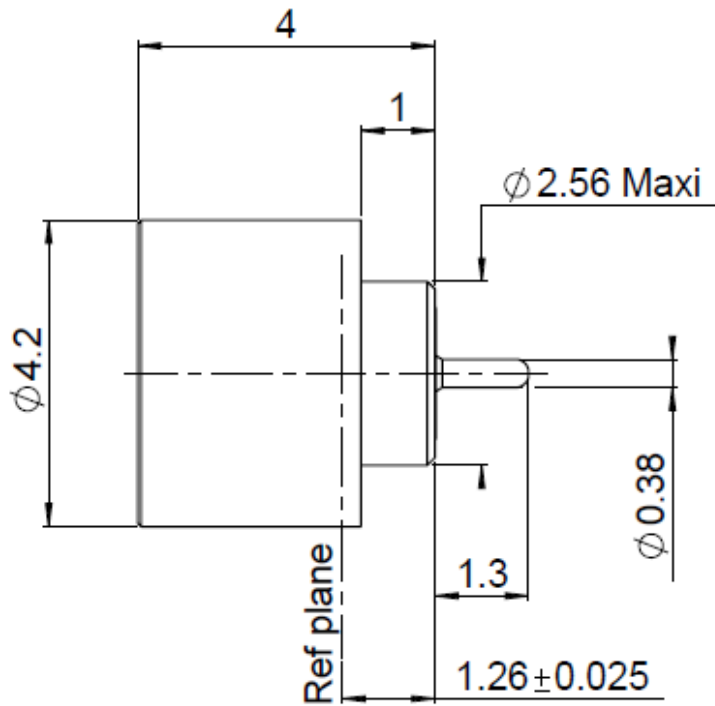
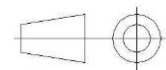


PAGE 1/3	ISSUE 21-12-15B	SERIES SMP	PART NUMBER R222645730
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All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	DILVER P1	GOLD OVER NICKEL
Center contact	DILVER P1	GOLD OVER NICKEL
Outer contact	-	-
Insulator	GLASS	-
Gasket	-	-
Others parts	-	-
-	-	-
-	-	-

PAGE 2/3	ISSUE 21-12-15B	SERIES SMP	PART NUMBER R222645730
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PACKAGING

Standard	Unit	Other
100	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-40	GHz
VSWR	1.15* +	0.0000	x F(GHz) Maxi
Insertion loss		0.12	√F(GHz) dB Maxi
RF leakage	- (- F(GHz) dB Maxi
Voltage rating		335	Veff Maxi
Dielectric withstanding voltage		500	Veff mini
Insulation resistance		5000	MΩ mini

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	10-8	Atm.cm3/s
Panel leakage		

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		6.8	N mini
Axial force – Opposite end		6.8	N mini
Torque			N.cm mini
Recommended torque			
Mating			N.cm
Panel nut			N.cm
Mating life		1000	Cycles mini
Weight		0.1500	g

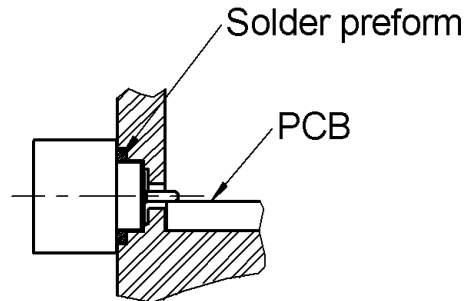
SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:
* to 18GHz

PAGE 3/3	ISSUE 21-12-15B	SERIES SMP	PART NUMBER R222645730
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1. Degrease and clean connector and box
2. Solder the connector on the panel
we advise SnAg4 Cu0.5, we recommend a low residue flux. Preheating at 100 °C. Take care not to exceed 260°C during solder operation
3. Solder the pin on the track
we advise SnAg4 Cu0.5, we recommend a low residue flux. Preheating at 100 °C (only for ceramic substrate). Take care not to exceed 260°C during solder operation

Panel mounting hole

